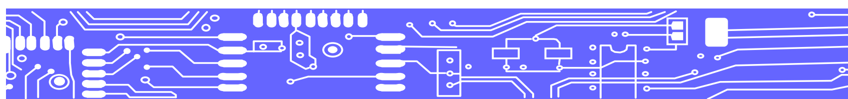
ECO+PLUS® series
Lead free SOLUTIONS you can TRUST



Hi-performance Lead Free Solder Paste

S3X58-M406L

■ Features

1) Ensures **OUTSTANDING** continual **PRINTABILITY** with super fine pitch (0.4mm/16mil) and CSP (>0.25mm dia.) applications and long stencil idle time.
2) **PERFECT MELTING** and wetting at super fine pitch (<0.4mm pitch) and micro components (<0.25mm dia CSP, 0603 chip).
3) Specially formulated flux chemistry ensures extremely **LOW VOIDING** with CSPs and broad contact area components.
4) **POWERFUL WETTING** with various metals, such as Alloy42 and Nickel.

■ Specifications

Application			Printing - Stencil
Product			**S3X58-M406L**
Alloy	Composition (%)		Sn96.5, Ag3.0, Cu0.5
	Melting point (°C)		217 - 218
	Shape		Spherical
	Particle size (µm)		20 - 38
Flux	Halide content (%)		0.0
	Surface insulation resistance *[1]	Initial value (Ω)	$> 1 \times 10^{13}$
		After humidification (Ω)	$> 1 \times 10^{11}$
	Aqueous solution resistivity*[2] (Ω cm)		$> 3 \times 10^{4}$
	Flux type		ROL0
Product	Flux content (%)		11.5
	Viscosity*[3] (Ps.S)		175
	Copper plate corrosion*[4]		Passed
	Solder spread factor (%)		> 85
	Tack time		> 72 hours
	Shelf life (below 10°C)		6 months
	Recommended reflow profile		Pre-heat : 110~190°C for 60~120sec. Peak temp. : 235~250°C Time > 220°C : >30sec/

1. SIR ....40°C×90%RH×96Hr
2. Aqueous solution resistivity ....In accordance with MIL specifications.
3. Viscosity ....Malcom spiral type viscometer, PCU-205 at 25°C 10rpm
4. Copper plate corrosion ....In accordance with JIS.

KOKI COMPANY LIMITED
32-1, Senju Asahi-cho, Adachi-ku, Tokyo 120-0026
Tel : (03) 5244-1521 Fax : (03) 5244-1525